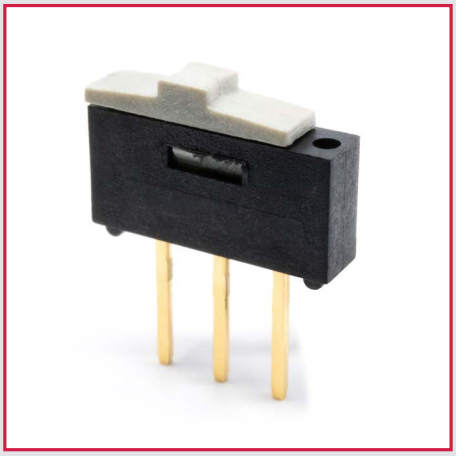
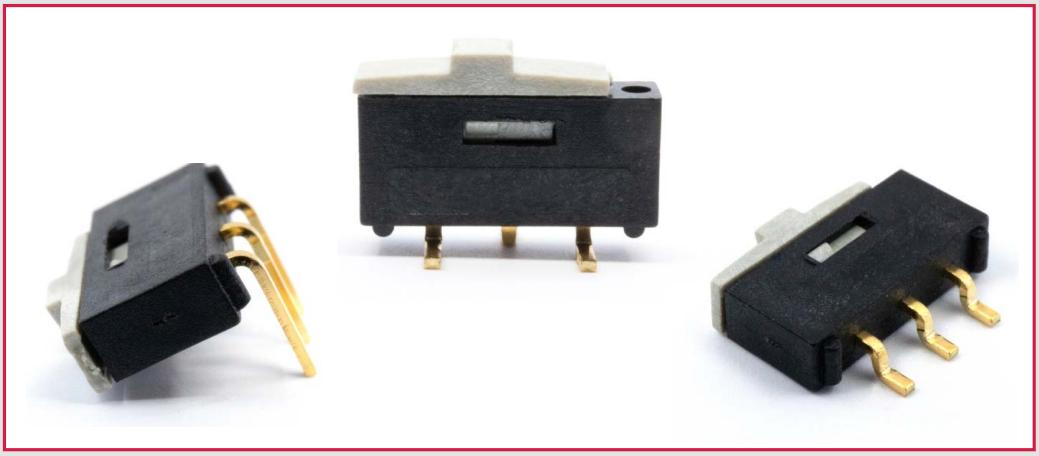
# EGJ1210 Series Slide Switch





## Specifications

**Contact Rating:** 300mA @ 24VDC
**Electrical Life:** 2,000 Cycles
**Mechanical Life:** 10,000 Cycles
**Contact Resistance:** 30mΩ Max
**Insulation Resistance:** 10,000MΩ Min @ 500VDC
**Dielectric Strength:** 500VAC for 1 Minute
**Operating Temperature:** -40°C to 85°C
**Storage Temperature:** -40°C to 85°C
**Travel:** 1.60mm
**Contact Arrangement:** SPDT

## Features & Benefits

**Surface mount and Through Hole PC board design**
**1.60mm travel**
**Compact design**
**250 gram force**
**SPDT function**

## Part Number Configurator

**Series** ☐☐☐☐☐☐☐
**EGJ1210**

**Actuator** ☐
**A** - 1.40mm

**Function** ☐
**A** - SPDT

**Terminal** ☐
**T1** - Through Hole
**T2** - Through Hole, Right Angle
**G1** - Gull Wing
**G2** - Gull Wing, Right Angle

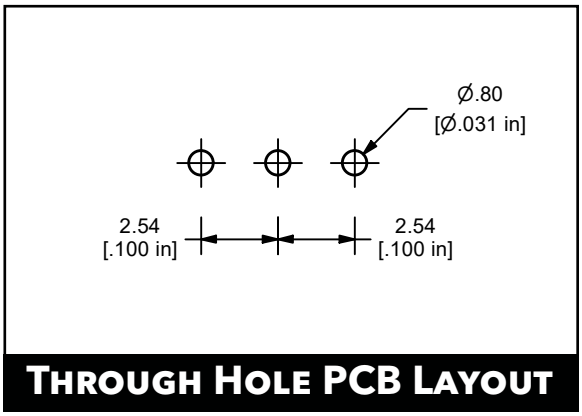
**Packaging** ☐
**(Blank)** - Bulk
**R** - Tape and Reel (Gull Wing Only)

NOTES:
*Any additional information or clarifications

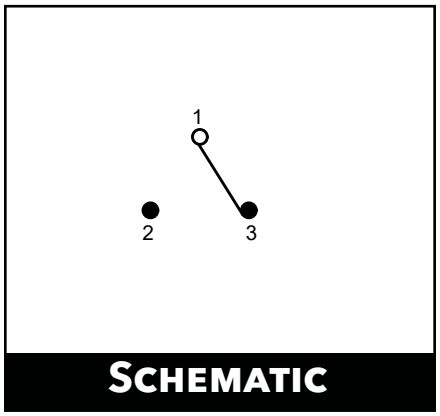
*Specifications subject to change without notice 10/29/2024*

# EGJ1210 Series Slide Switch - Body Dimensions

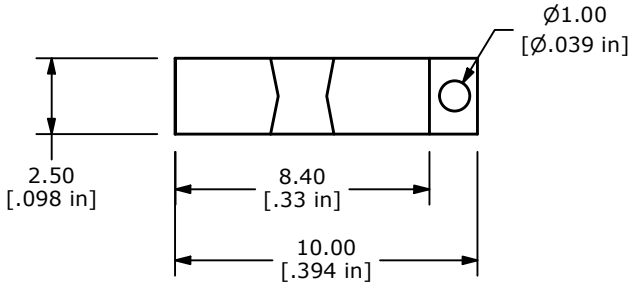
## Through Hole

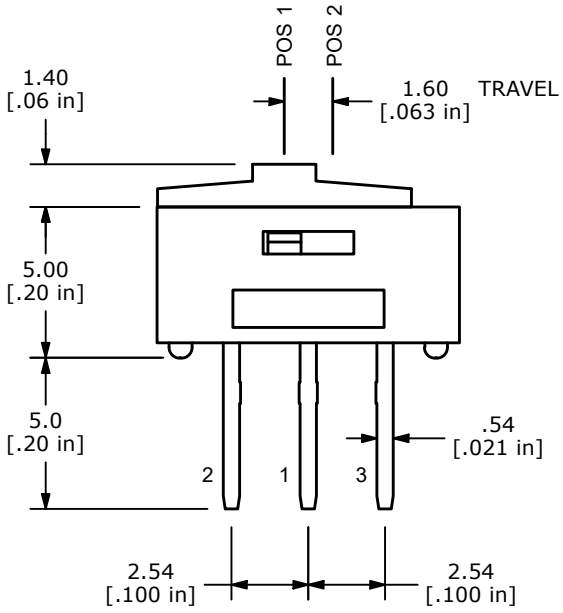


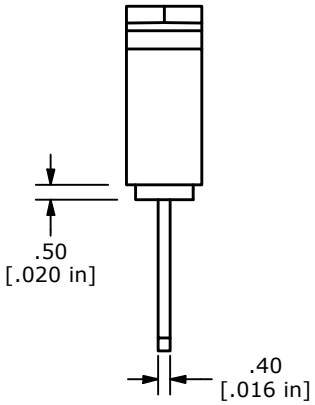

Through Hole PCB Layout




Schematic

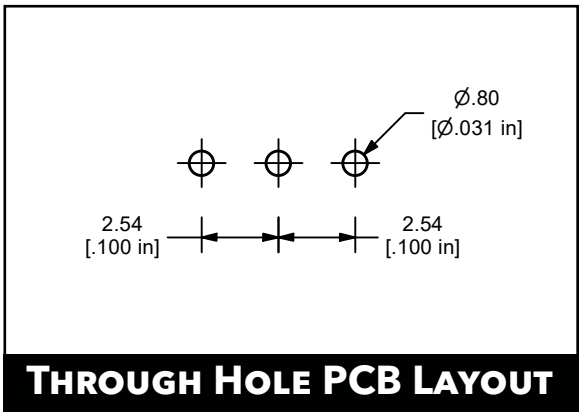


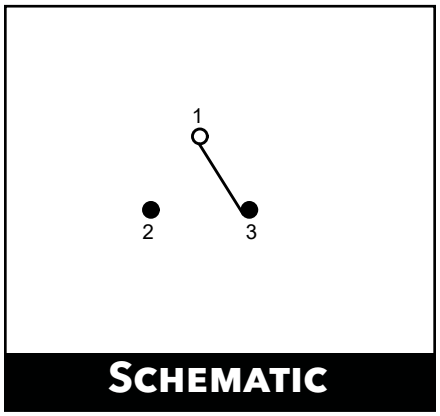



# EGJ1210 Series Slide Switch - Body Dimensions

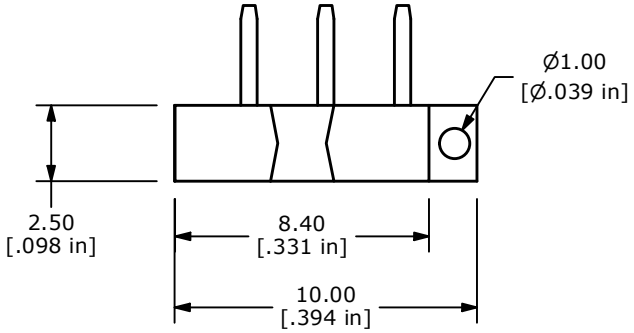
## Through Hole Right Angle

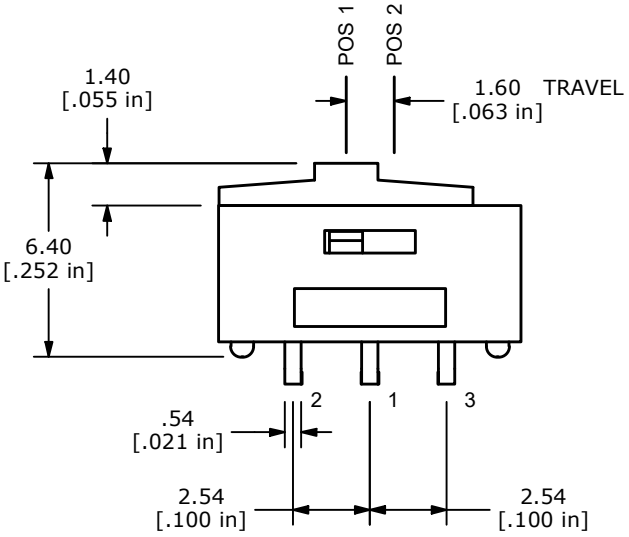


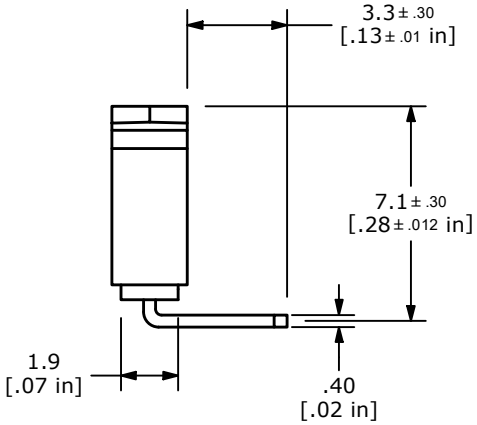

Through Hole PCB Layout




Schematic

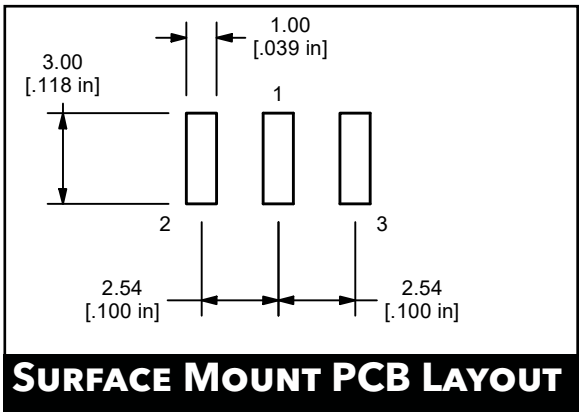


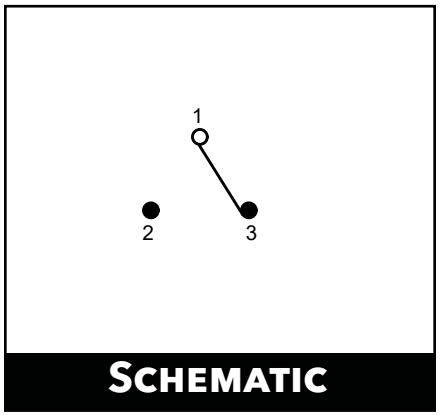



# EGJ1210 Series Slide Switch - Body Dimensions

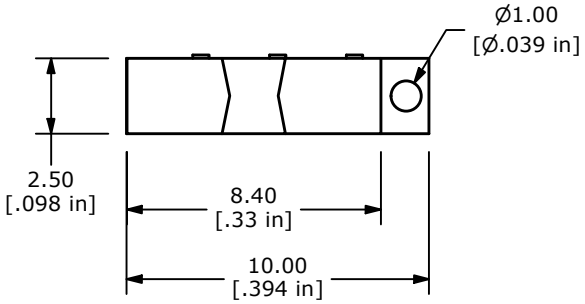
## Gull Wing

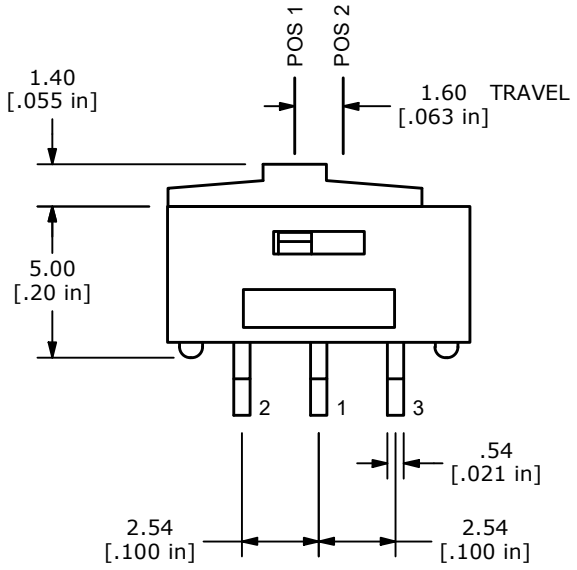


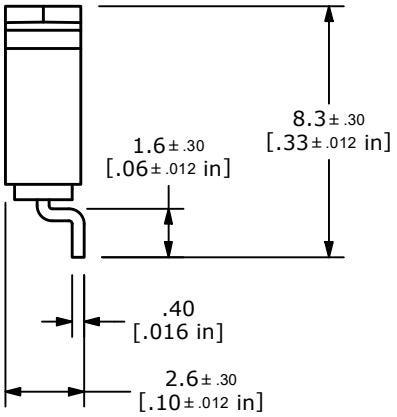

Surface Mount PCB Layout




Schematic

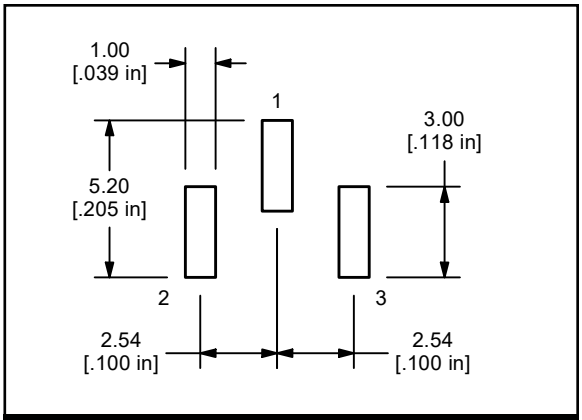


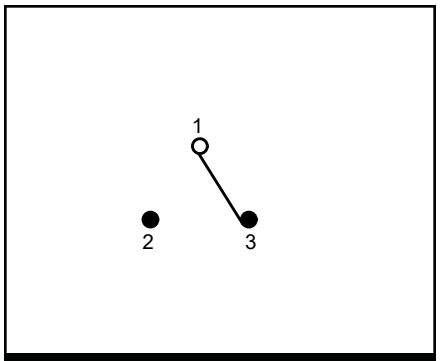



# EGJ1210 Series Slide Switch - Body Dimensions

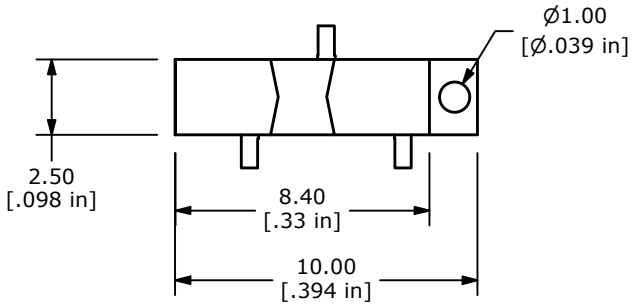
## Gull Wing Right Angle

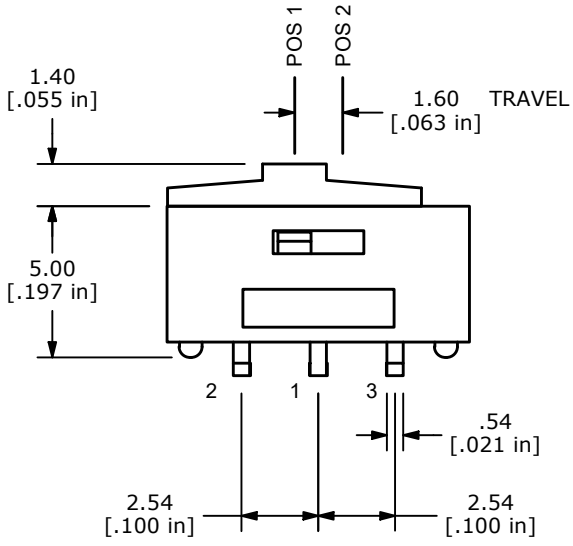


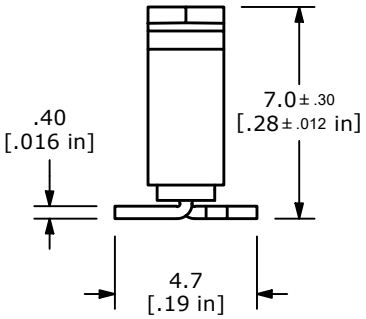

Surface Mount PCB Layout




Schematic

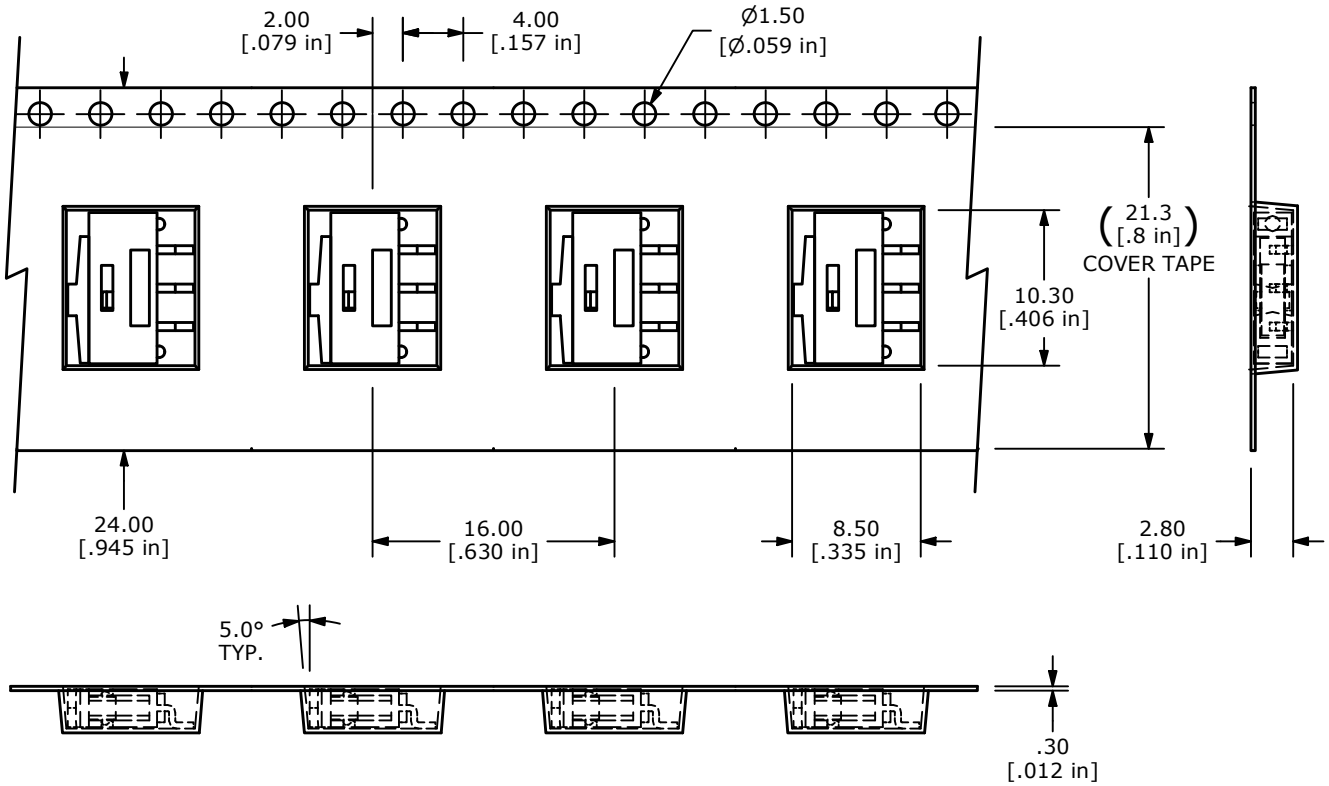


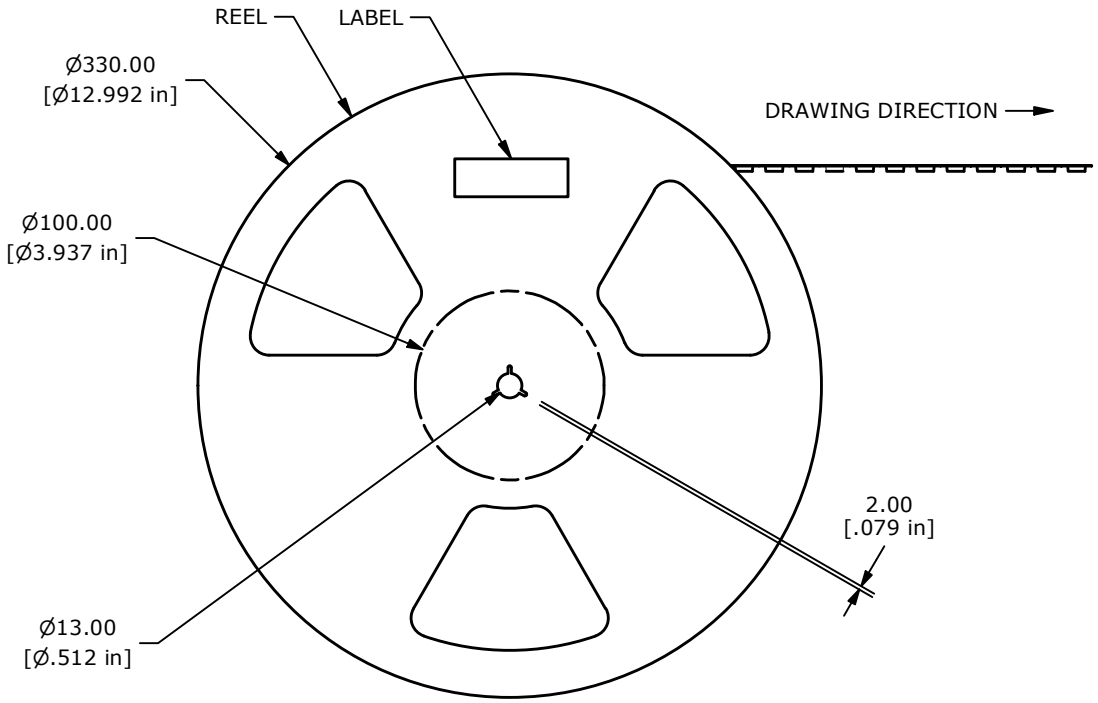



# EGJ1210 Series Slide Switch - Body Dimensions

## Tape and Reel



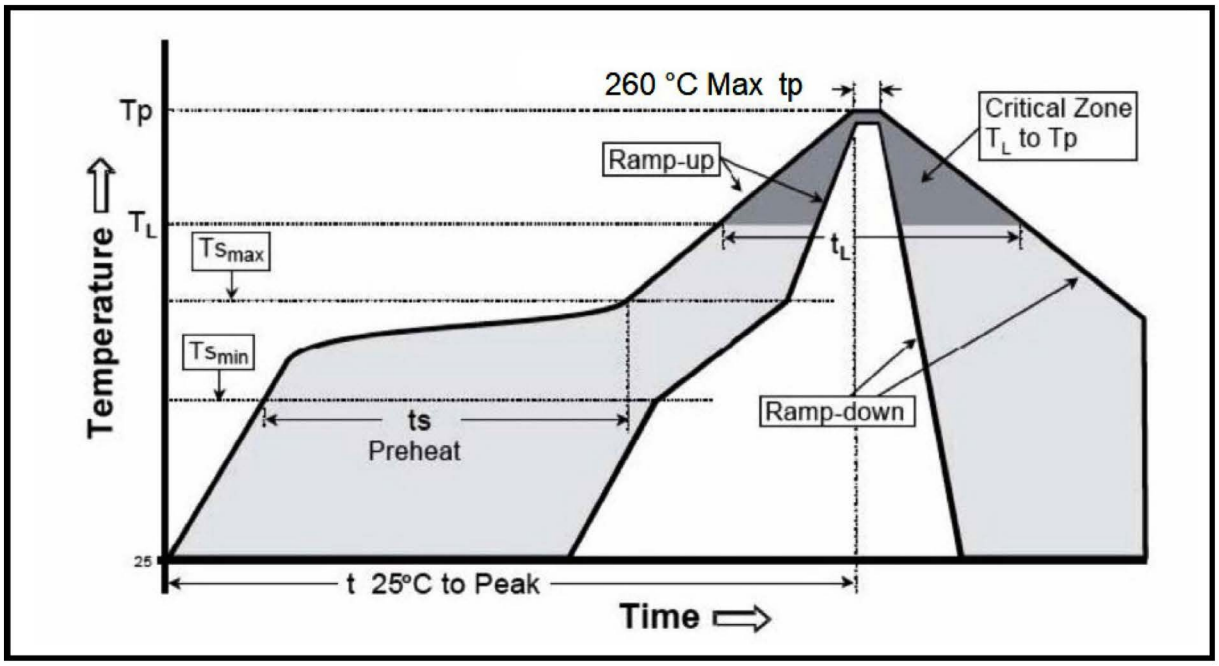



# EGJ1210 Series Slide Switch

## Recommended Solder Process

Most contamination problems can be prevented by exercising care during the cleaning and soldering process. Care should be taken not to immerse or spray unsealed switches during flux removal. Contact E-Switch for specific soldering recommendations and specifications not shown. Generalized soldering procedures are outlined below.

## "TYPICAL" SMT REFLOW (Pb and Pb-Free)

| Profile Feature | Sn-Pb Eutectic Assembly | Pb-Free Assembly |
|---|---|---|
| Average Ramp-Up Rate ($Ts_{max}$ to Tp) | 3 °C/second max. | 3 °C/second max. |
| **Preheat**<br>-Temperature Min ($Ts_{min}$)<br>-Temperature Max ($Ts_{max}$)<br>-Time ($ts_{min}$ to $ts_{max}$) | <br>100 °C<br>150 °C<br>60-120 seconds | <br>150 °C<br>200 °C<br>60-180 seconds |
| Time Maintained above:<br>-Temperature ($T_L$)<br>-Time ($t_L$) | <br>183 °C<br>60-150 seconds | <br>217 °C<br>60-150 seconds |
| Time within 5 °C of actual Peak Temperature (tp) | 10-30 seconds | 20-40 seconds |
| Ramp-Down Rate | 6 °C/second max. | 6 °C/second max. |
| Time 25 °C to Peak Temperature | 6 minutes max. | 8 minutes max. |

***Note 1:*** *All temperatures refer to topside of the package, measured on the package surface.*